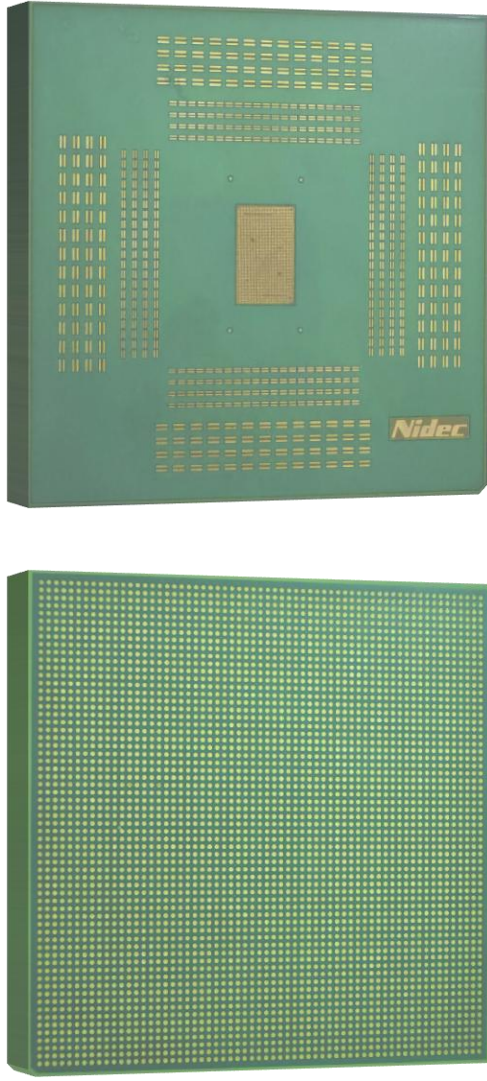
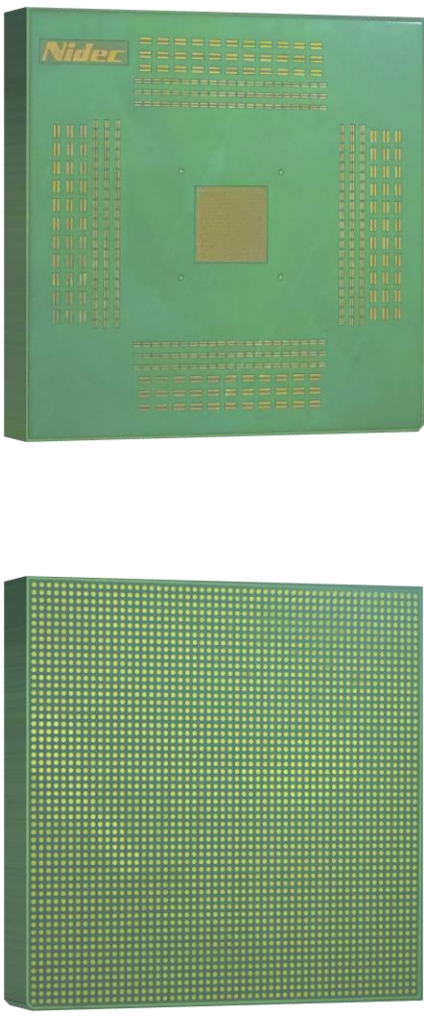
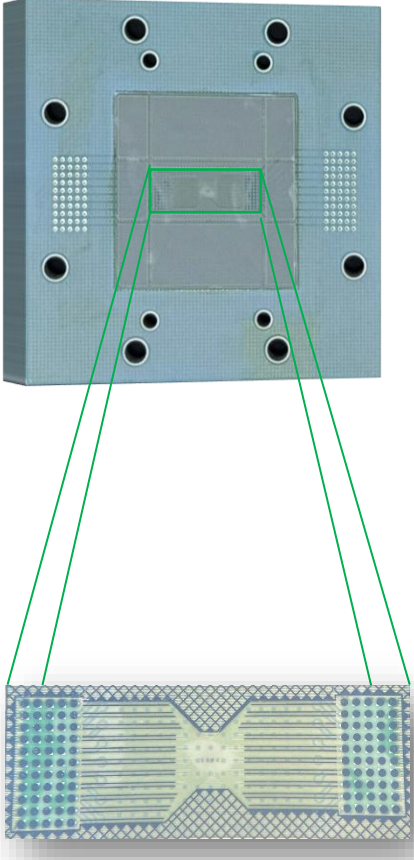




ST MLO Substrate

with Build-up **SAP** technology

SAP = Semi Additive Process

	ST MLO(SAP)			2.5D ST MLO Thin Film + SAP
Sample				
O.D.	65mmSQ	56mmSQ	23.2mmSQ	26mmSQ(RDL) 50mmSQ(MLO)
Layer#	30	←	26	-
Pad Pitch	162um	←	70um	25um
Pad DIA.	120um	←	55um	15um
L/S	20/25um	←	17/25um	3/3um

特征 Characteristics

以大批量生产为前提的精细线路积层**SAP ST MLO**基板，现已可实现小批量试制级别的定制生产。诚邀您将其运用于产品开发环节。

SAP technology only by mega suppliers is now available even for small lot/ prototype production as an ideal product development tool.

- 欢迎定制设计
 - 可实现30层以上堆叠
 - 可使用薄型核心基板(~40um)
- Custom design welcome
 - Capable of more than 30 layers of stacking
 - Thin core material (~40umt)

SAP Design Rule

	~2025	2026 1H~
Via DIA.	25 um	←
Min. Via Land DIA.	50 um	←
Min. L/S	20 / 25 um	15 / 15 um
Min. Probe Pad Pitch	75 um	65 um
Min. Probe Pad DIA.	55 um	50 um



MLO Substrate

with Build-up **SAP** technology

SAP = Semi Additive Process

Sample		
O.D.	23mmSQ	←
Structure	2/2/2	←
Thickness	1mm	250um
Pad Pitch	120um	←
Pad DIA.	70um	←
L/S	17/20um	←

特 征 Characteristics

采用**SAP**工艺可实现少量、试制级别的**MLO**基板定制生产。
Custom **MLO** substrates can be produced in small quantities at the prototype level using the **SAP** process.

作为薄物对应方案，可采用全层**SAP**工法进行制作。
Thin substrates can be manufactured using the full-layer **SAP** process.

请使用我们的产品——从厚款到薄款——助力您的产品开发。
Please utilize our products—from thick to thin—to assist in your product development.

- 欢迎定制设计
 - 可使用薄型核心基板(~40um)
 - 小间距与小孔径
- Custom design welcome
 - Thin core material (~40umt)
 - Small Pitch and Small Via Diameter

SAP Design Rule

	~2025	2026 1H~
Via DIA.	25 um	←
Min. Via Land DIA.	50 um	←
Min. L/S	20 / 25 um	15 / 15 um
Min. C4 Pad Pitch	75 um	65 um
Min. C4 Pad DIA.	55 um	50 um